

Attorney Docket No. 9180-30

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Jong-Rong Jan et al;

Application No.: not yet assigned

Filed: concurrently herewith

For: METHODS OF SELECTIVELY BUMPING INTEGRATED CIRCUIT  
SUBSTRATES AND RELATED STRUCTURES

Date: February 17, 2004

MAIL STOP PATENT APPLICATION

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97(b)**

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the waiver by the U.S. Patent and Trademark Office of requirements under 37 C.F.R. § 1.98(a)(2)(i) for all U.S. national patent applications filed after June 30, 2003 and for all international applications that have entered the national stage under 35 USC § 371 after June 30, 2003.

It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. § 1.56 and Section 609 of the MPEP.

No fee is believed due. However, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

Respectfully submitted,

  
Scott C. Hatfield

Registration No. 38,176

Myers Bigel Sibley & Sajovec, P.A.

P. O. Box 37428

Raleigh, North Carolina 27627

Telephone: (919) 854-1400

Facsimile: (919) 854-1401

Customer No. 20792

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Joyce Paoli

Substitute form 1449A/PTO			<b>Complete if Known</b>		
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)			Application Number	not yet assigned	
			Filing Date	concurrently herewith	
			First Named Inventor	Jong-Rong Jan et al;	
			Group Art Unit	not yet assigned	
			Examiner Name	not yet assigned	
Sheet	1	of	1	Attorney Docket Number	9180-30

U.S. PATENTS AND PATENT PUBLICATIONS					
Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
	1.	US-3,625,837		Nelson et al;	12/07/1971
	2.	US-5,130,275		Dion	07/14/1992
	3.	US-5,211,807		Yee	05/18/1993
	4.	US-5,462,638		Datta et al;	10/31/1995
	5.	US-5,470,787		Greer	11/28/1995
	6.	US-5,471,092		Chan et al;	11/28/1995
	7.	US-5,759,437		Datta et al;	06/02/1998
	8.	US-5,796,168		Datta et al;	08/18/1998
	9.	US-5,937,320		Andricacos et al;	08/10/1999
	10.	US-6,015,505		David et al;	01/18/2000
	11.	US-6,130,170		David et al;	10/10/2000
	12.	US-6,332,988		Berger, Jr. et al;	12/25/2001
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FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Office	Number	Kind Code (if known)		

OTHER NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published		
	13.	R.B. Danzl and Allen McLaurin; "The Use of Concentrated Hydrogen Peroxide for the Removal of a TiW ARC from Aluminum Bond Pads" IEEE/CPMT Int'l Electronics Manufacturing Technology Symposium (1997) pp 99-104.		
	14.	Akira Furuya and Yoshio Ohshita; "Ti concentration effect on adhesive energy at Cu/TiW interface"; Journal of Applied Physics, Vol. 84, No. 9, (Nov 1998) pp 4941-4944.		
	15.	Julia Hawley and Van-Vo; "Solutions to Catastrophic Yield Problems in MCM-D Interconnect Production"; 1998 International Conference on Multichip Modules and High Density Packaging; pp 118-123.		

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.